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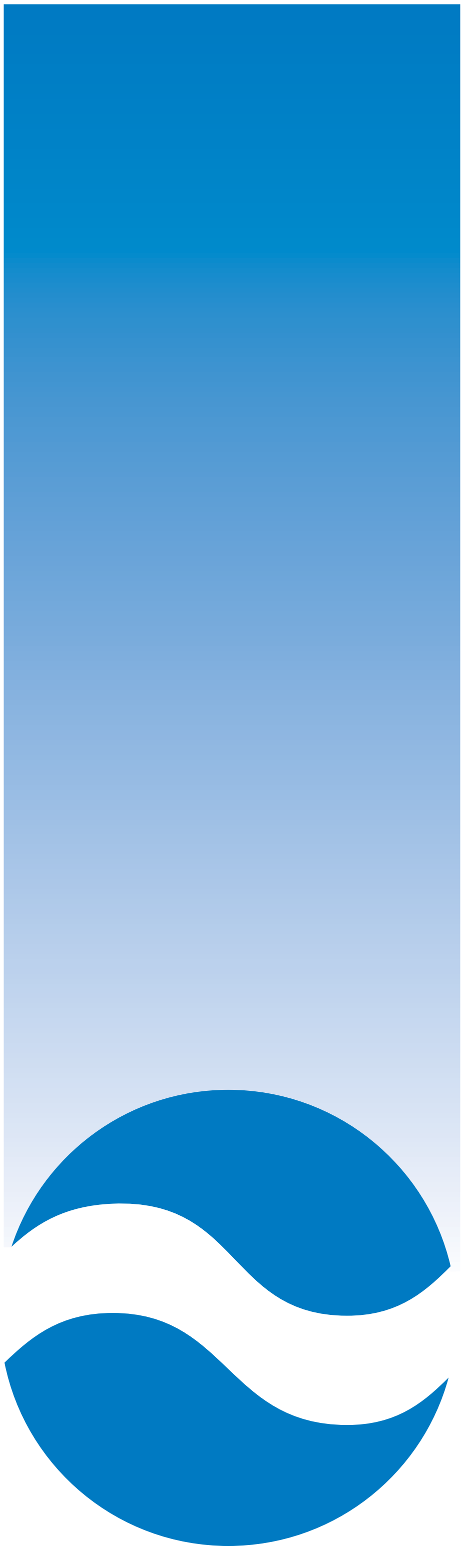
JOINT INDUSTRY STANDARD

Requirements for Soldering Fluxes



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- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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IPC J-STD-004B with Amendment 1

Requirements for Soldering Fluxes

A standard developed by the Flux Specifications Task Group (5-24a) of the Assembly and Joining Processes Committee (5-20) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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